

Product Data Sheet

DIN 41612 Straight-type spring-loaded connector, Type E,
Part No. 108-60084

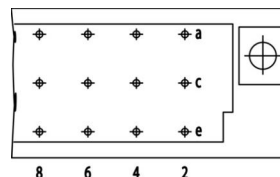
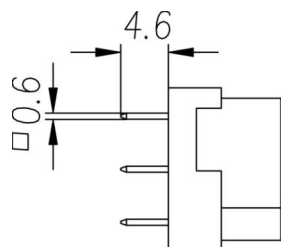
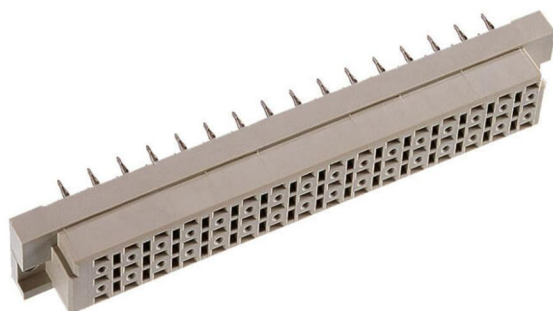


Illustration similar



Parallel



Perpendicular



Press-fit



Power



Rugged

- Connector length: 4.6 mm
- Connection 0.6 x 0.6
- Number of poles: 48
- Press-fit technology
- Grade 2



» to product on www.ept.de



» to product group DIN 41612

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Technical Specifications

Basics

Specification	IEC 60603-2 (DIN 41612)
Performance Level	2
No. of Contacts	48
Termination Technology	Press-fit technology
Termination Length	4.6 mm
Board-to-Board Distance	17.85 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	Glass-fiber-reinforced PBT, UL 94 V-0
CTI value <i>IEC 60112</i>	200
Contact Material	copper alloy

Mechanical

Pitch	5.08 mm
Mating Force	60 N
Separating Force per Pin	> 0.15 N
Durability	400 insertion cycles

Electrical

Operational Current	5.6 A
Contact Resistance	15 mΩ
Clearance and Creepage	≥ 3.0 mm
Insulation Resistance	> 10 ⁶ MΩ
Test Voltage	1500 V

Approval / Compliance

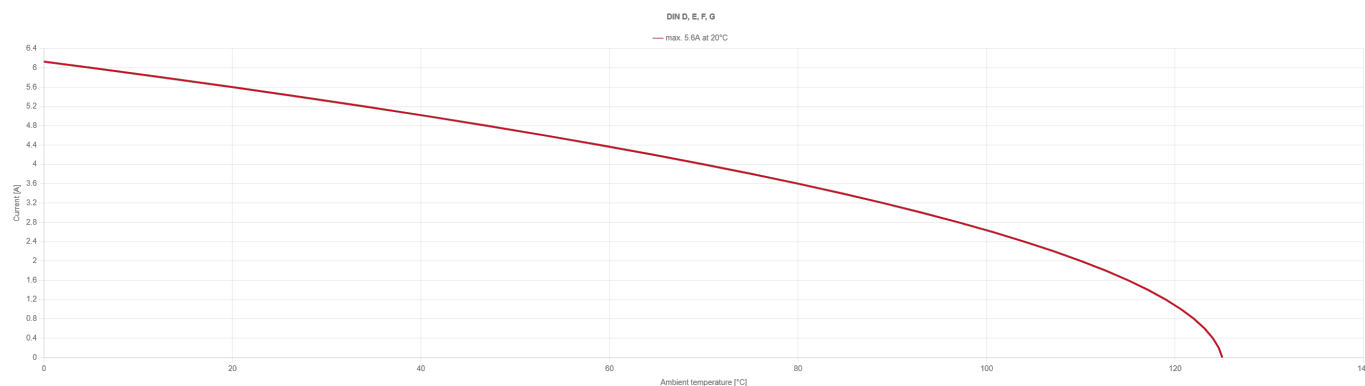
UL file	E130314
Environment	RoHS compliant

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Derating Diagram



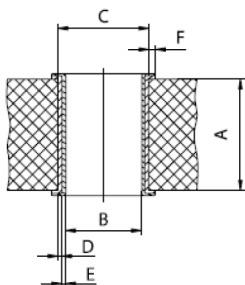
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Leiterplatten
Nennloch	Ø 1.0 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 1.0 +0.09 / -0.06 mm
C Grundbohrung	1.15 ±0.025 mm
D Cu Schicht	min. 25 µm
E Oberfläche	chem. Sn Schicht, max. 1.5 µm
F Restring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nennloch	Ø 1.0 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 1.0 +0.09 / -0.06 mm
C Grundbohrung	1.15 ±0.025 mm
D Cu Schicht	min. 25 µm
E Oberfläche	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Restring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nennloch	Ø 1.0 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 1.0 +0.09 / -0.06 mm
C Grundbohrung	1.15 ±0.025 mm
D Cu Schicht	min. 25 µm
E Oberfläche	OSP, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Restring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nennloch	Ø 1.0 mm
A Leiterplattendicke	min. 1.44 mm
B Endloch	Ø 1.0 +0.09 / -0.06 mm
C Grundbohrung	1.15 ±0.025 mm
D Cu Schicht	min. 25 µm
E Oberfläche	HAL Sn, 5 - 15 µm
F Restring	min. 0.1 mm

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Modifications

Available on request

- without mounting flange
- Special lengths for connections
- Grade I + III or custom
- Special configuration

Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)